

INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application No.	10/822,424
	Filing Date	April 12, 2004
	First Named Inventor	Bulent M. Basol
	Art Unit	4742 1795
(Multiple sheets used when necessary)	Examiner	Zulmariam Mendez
SHEET 1 OF 2	Attorney Docket No.	NVLUS.029CP1(5296)

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Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
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NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹
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Examiner Signature	/Zulmariam Mendez/	Date Considered	10/28/2007
<p>*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>			

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Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ¹
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